

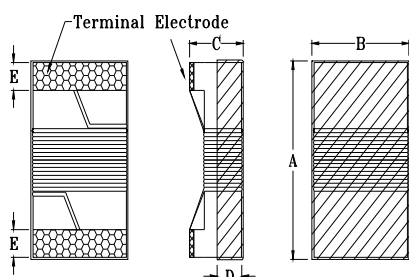
High Frequency Winding Type Chip Inductor SWI0402F-SERIES-HC

1. Features

1. Ceramic core wire wound construction.
2. No batch to batch variations in inductance.
3. High Reliability due to ceramic wire wound construction.
4. High frequency application.
5. Small footprint as well as low profile.
6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
7. Operating temperature-40~+125℃ (Including self - temperature rise)



2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SWI0402	1.09±0.10	0.60±0.10	0.56±0.10	0.25±0.15	0.23±0.10

Unit:mm

3. Part Numbering

SWI	0402	F	-	1N2	B	-	HC
A	B	C		D	E		F

A: Series

B: Dimension

C: Material

D: Inductance

E: Inductance Tolerance

F: Control S/N

LxW

Ceramic

1N2=1.2nH

B=±0.1nH, G=±2%, J=±5%, K=±10%.

4. Specification

Part Number	Inductance (nH)	Tolerance	Q min.	Test Frequency (Hz)	Isat(mA) max.	Irms(mA) max.	DCR (Ω) max.	SRF (GHz) min.
SWI0402F-1N2□-HC	1.2	B,J,K	10	0.2V/250M	640	640	0.140	10.40
SWI0402F-2N2□-HC	2.2	B,J,K	19	0.2V/250M	960	960	0.070	10.80
SWI0402F-2N4□-HC	2.4	B,J,K	15	0.2V/250M	790	790	0.068	10.50
SWI0402F-2N7□-HC	2.7	B,J,K	16	0.2V/250M	640	640	0.120	10.40
SWI0402F-3N3□-HC	3.3	J,K	19	0.2V/250M	840	840	0.066	7.00
SWI0402F-3N6□-HC	3.6	J,K	19	0.2V/250M	840	840	0.066	6.80
SWI0402F-3N9□-HC	3.9	J,K	19	0.2V/250M	840	840	0.066	6.00
SWI0402F-4N3□-HC	4.3	J,K	18	0.2V/250M	700	700	0.091	6.00
SWI0402F-4N7□-HC	4.7	J,K	15	0.2V/250M	640	640	0.130	4.77
SWI0402F-5N6□-HC	5.6	J,K	20	0.2V/250M	760	760	0.083	4.80
SWI0402F-6N2□-HC	6.2	J,K	20	0.2V/250M	760	760	0.083	4.80
SWI0402F-6N8□-HC	6.8	J,K	20	0.2V/250M	680	680	0.083	4.80

Part Number	Inductance (nH)	Tolerance	Q min.	Test Frequency (Hz)	Isat(mA) max.	Irms(mA) max.	DCR (Ω) max.	SRF (GHz) min.
SWI0402F-7N5□-HC	7.5	J.K	22	0.2V/250M	680	680	0.100	4.80
SWI0402F-8N2□-HC	8.2	J.K	22	0.2V/250M	680	680	0.100	4.40
SWI0402F-8N7□-HC	8.7	J.K	18	0.2V/250M	480	480	0.200	4.10
SWI0402F-9N0□-HC	9.0	J.K	22	0.2V/250M	680	680	0.100	4.16
SWI0402F-9N5□-HC	9.5	J.K	18	0.2V/250M	480	480	0.200	4.00
SWI0402F-10N□-HC	10	J.K	21	0.2V/250M	480	480	0.200	3.90
SWI0402F-11N□-HC	11	J.K	24	0.2V/250M	640	640	0.120	3.68
SWI0402F-12N□-HC	12	J.K	24	0.2V/250M	640	640	0.120	3.60
SWI0402F-13N□-HC	13	J.K	24	0.2V/250M	440	440	0.210	3.45
SWI0402F-15N□-HC	15	J.K	24	0.2V/250M	560	560	0.170	3.28
SWI0402F-16N□-HC	16	J.K	24	0.2V/250M	560	560	0.220	3.10
SWI0402F-18N□-HC	18	J.K	25	0.2V/250M	420	420	0.230	3.10
SWI0402F-19N□-HC	19	J.K	24	0.2V/250M	480	480	0.200	3.04
SWI0402F-20N□-HC	20	J.K	25	0.2V/250M	420	420	0.250	3.00
SWI0402F-22N□-HC	22	J.K	25	0.2V/250M	400	400	0.300	2.80
SWI0402F-23N□-HC	23	J.K	22	0.2V/250M	400	400	0.300	2.72
SWI0402F-24N□-HC	24	J.K	25	0.2V/250M	400	400	0.300	2.70
SWI0402F-27N□-HC	27	J.K	24	0.2V/250M	400	400	0.300	2.48
SWI0402F-30N□-HC	30	G.J.K	25	0.2V/250M	400	400	0.350	2.35
SWI0402F-33N□-HC	33	G.J.K	24	0.2V/250M	400	400	0.400	2.35
SWI0402F-36N□-HC	36	G.J.K	24	0.2V/250M	320	320	0.440	2.32
SWI0402F-39N□-HC	39	G.J.K	25	0.2V/250M	200	200	0.550	2.10
SWI0402F-40N□-HC	40	G.J.K	24	0.2V/250M	320	320	0.650	2.24
SWI0402F-43N□-HC	43	G.J.K	25	0.2V/250M	100	100	0.810	2.03
SWI0402F-47N□-HC	47	G.J.K	25	0.2V/250M	150	150	0.830	2.10
SWI0402F-51N□-HC	51	G.J.K	25	0.2V/250M	100	100	0.820	1.75
SWI0402F-56N□-HC	56	G.J.K	22	0.2V/250M	100	100	0.970	1.76
SWI0402F-68N□-HC	68	G.J.K	22	0.2V/250M	100	100	1.120	1.62
SWI0402F-77N□-HC	77	J.K	22	0.2V/250M	50	50	1.800	1.26
SWI0402F-82N□-HC	82	G.J.K	22	0.2V/250M	50	50	1.550	1.26
SWI0402F-R10□-HC	100	G.J.K	22	0.2V/250M	30	30	2.000	1.16
SWI0402F-R12□-HC	120	J.K	22	0.2V/250M	50	50	2.400	1.00

Note:

- All test data referenced to 25°C ambient.

5. Recommended PC Board Pattern

Chip size						Land Patterns For Reflow Soldering			
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWI	0402	1.09±0.1	0.60±0.1	0.56±0.1	0.25±0.15	0.23±0.1	1.46	0.46	0.66

